

FYLS – 5050RGB

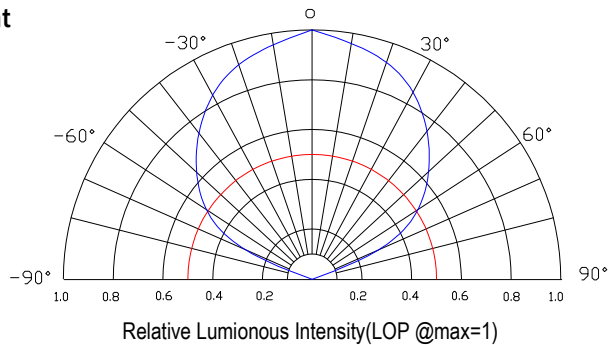
Radiation pattern.

Features:

- Compatible with automatic placement equipment
- Compatible with reflow solder process.

Applications:

- Automotive-Telecommunication
- Indicators
- LCD Back-lights
- Illuminations



Descriptions:

- Dice material: InGaN.
- Emitting Color: White
- Lens Color: Yellow Diffused.

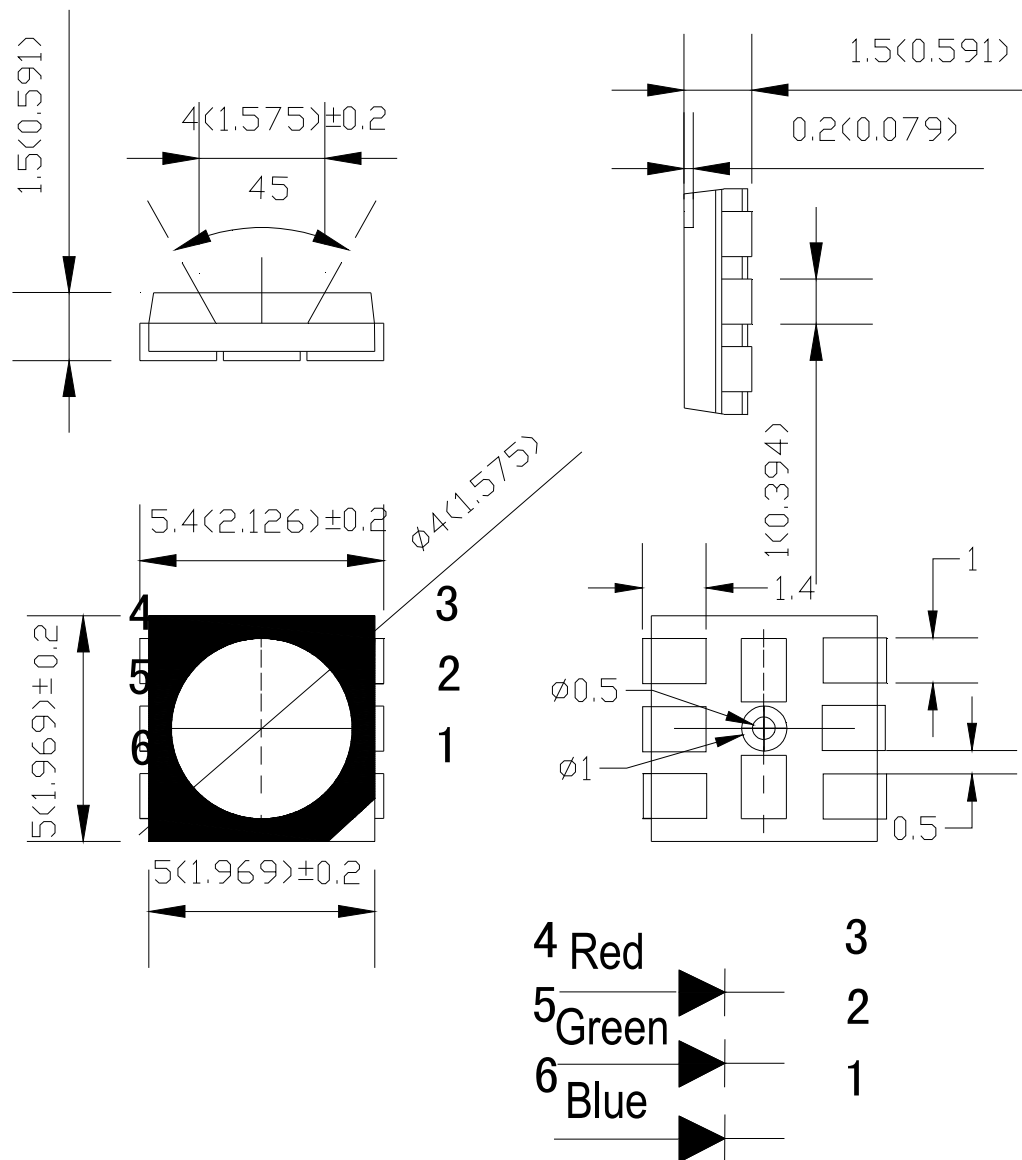
Absolute maximum ratings(Ta=25 °c)

Parameter	MAX.		Unit
Power Dissipation	R	55	mW
	G	75	
	B	75	
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse)	100		mA
Continuous Forward Current	300		mA
Derating Linear From 25°C	0.4		mA/°C
Operating Temperature Range	-30°C to +80°C		
Storage Temperature Range	-40°C to +100°C		
Lead Soldering Temperature[4mm(.157") From Body]	260°C for 5 Seconds		

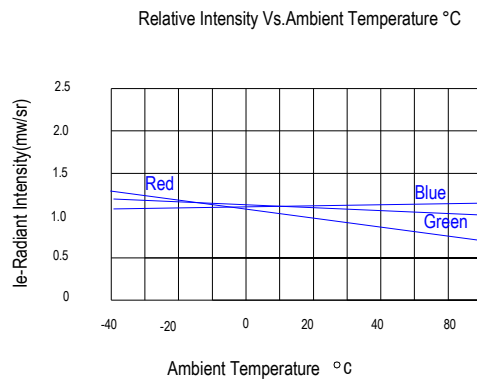
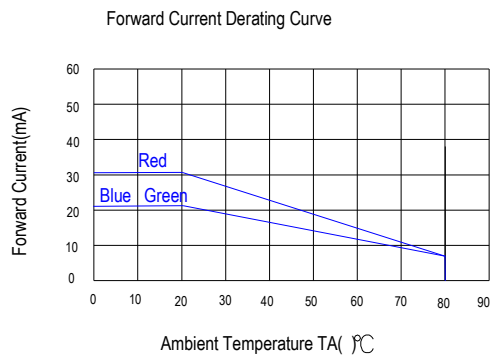
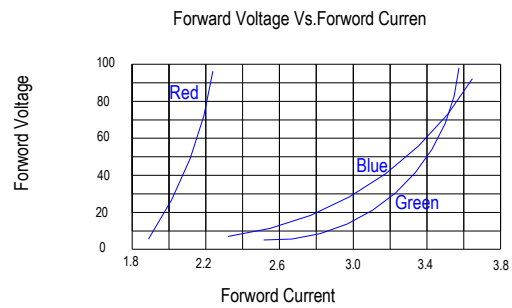
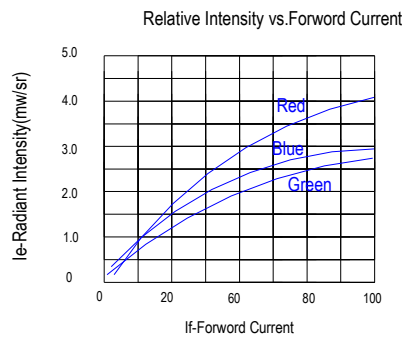
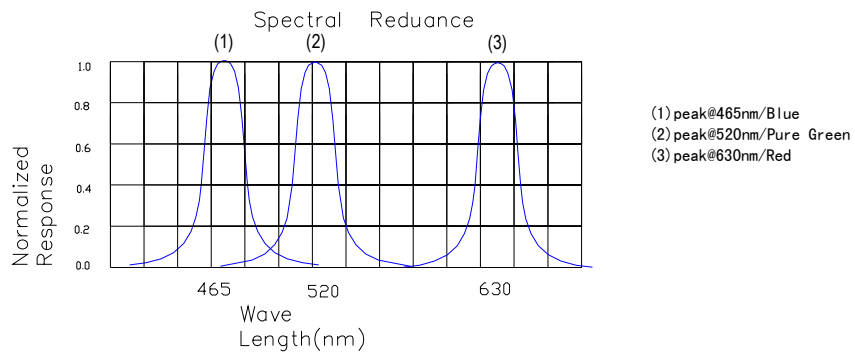
Electrical and optical characteristics(Ta=25 °c)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	IV	—	R: 600 G: 1300 B: 400	—	mcd	IF=20mA
Viewing Angle	2θ1/2	—	120	—	Deg	
Wavelength	λd	R:620		R:630	nm	
		G:520		G:525		
		B:465		B:470		
Forward Voltage	VF	3.0	R: 2.2 G: 3.2 B: 3.2	-	V	
Reverse Current	IR			5	μA	VR=5V

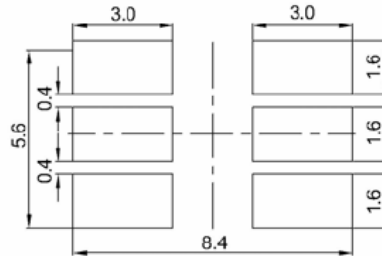
Package Dimensions



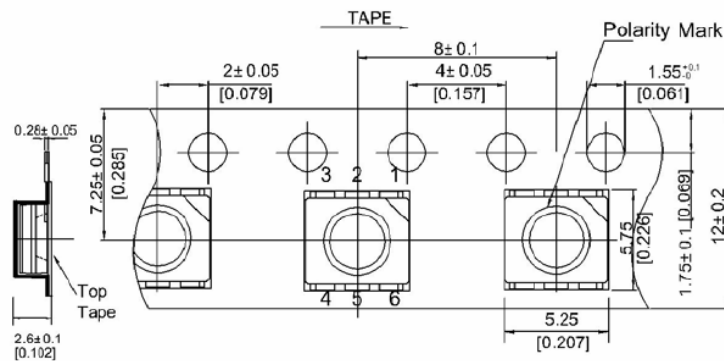
Typical Electrical Characteristics Curves (25 °c Ambient Temperature Unless Otherwise Noted)



Recommended Soldering Pattern
(Units : mm)

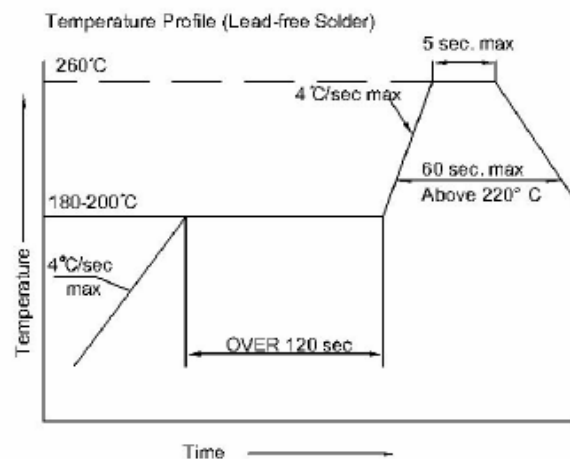
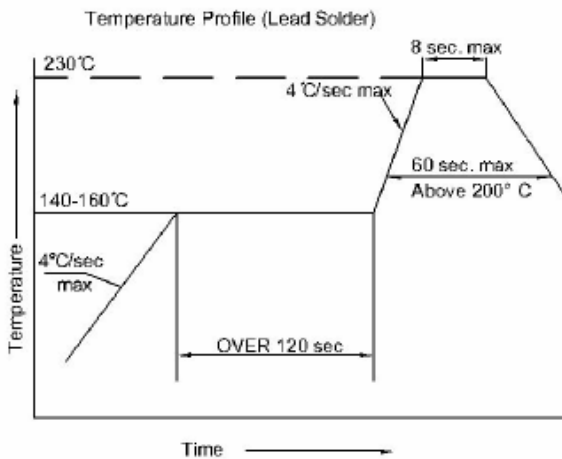


Tape Specifications (Units : mm)



SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



◆ Packing and Shipping Spec.

